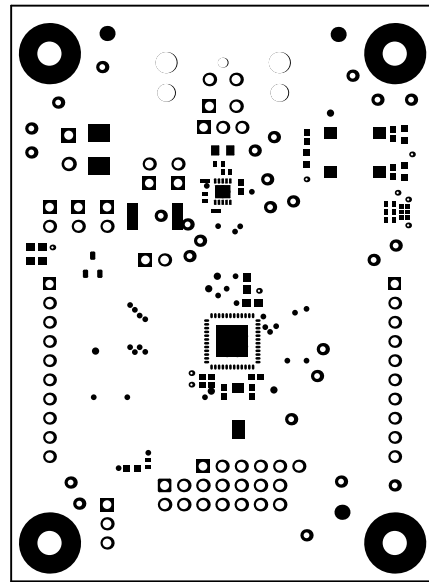
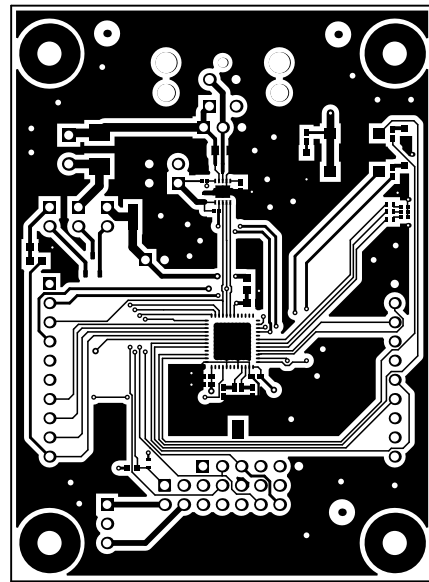


SH-J3
SH-J7
SH-J8
SH-J9
SH-J19

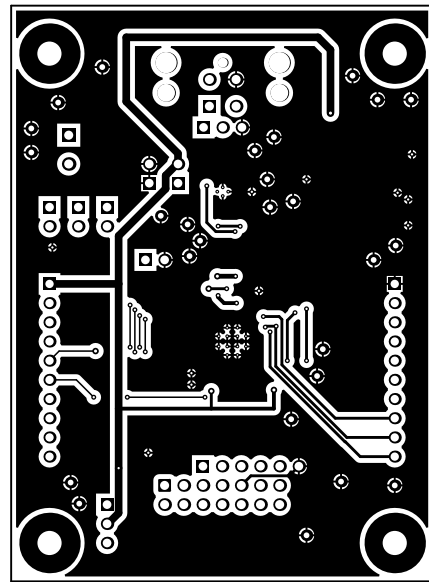
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01250		
PLOT NAME = Top Overlay	GENERATED : 6/30/2017 11:50:49 AM	TEXAS INSTRUMENTS	



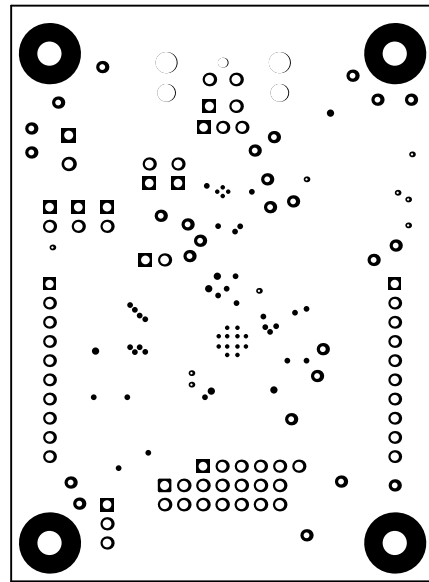
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01250		
PLOT NAME = Top Solder Mask	GENERATED : 6/30/2017 11:50:50 AM	TEXAS INSTRUMENTS	



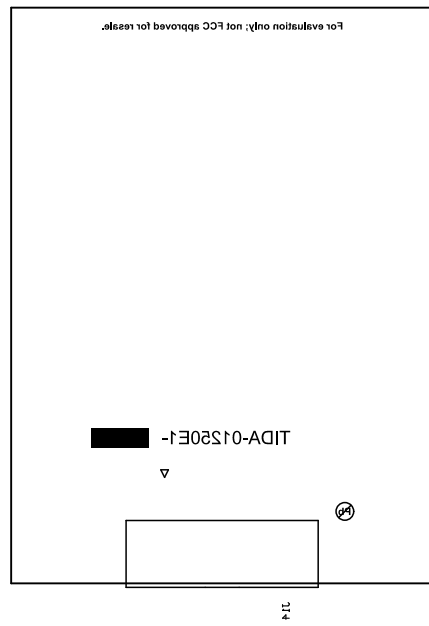
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: TIDA-01250		
PLOT NAME = Top Layer	GENERATED : 6/30/2017 11:50:51 AM	TEXAS INSTRUMENTS	



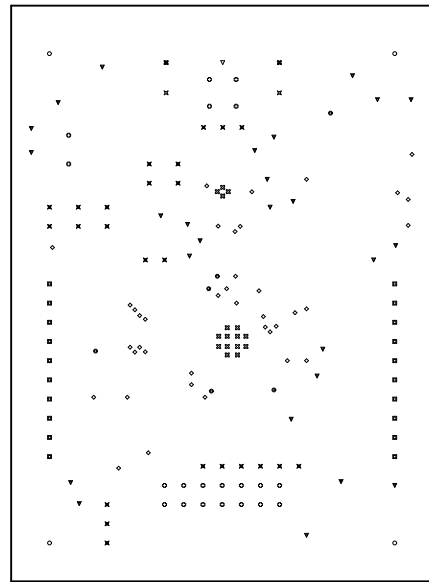
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: TIDA-01250		
PLOT NAME = Bottom Layer	GENERATED : 6/30/2017 11:50:53 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01250		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/30/2017 11:50:54 AM	TEXAS INSTRUMENTS	

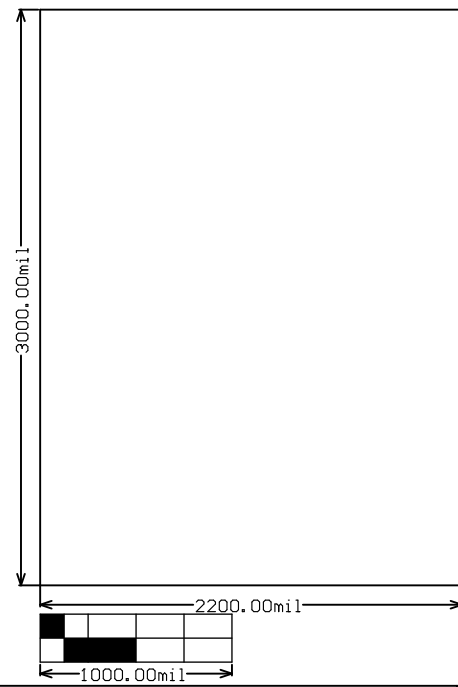


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01250		
PLOT NAME = Bottom Overlay	GENERATED : 6/30/2017 11:50:56 AM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
▽	1	51.18mil (1.300mm)	NPTH	Round	Top Layer - Bottom Layer	
✕	2	92.52mil (2.350mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	2	110.24mil (2.800mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	16	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
◇	39	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
○	6	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
▽	26	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
■	20	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	
✕	24	45.28mil (1.150mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	20	47.24mil (1.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
	160 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01250		
PLOT NAME = Drill Drawing	GENERATED : 6/30/2017 11:50:57 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01250	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01250		
PLOT NAME = Board Dimensions	GENERATED : 6/30/2017 11:50:59 AM	TEXAS INSTRUMENTS	

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